### Multilayer Ceramic Chip Capacitors

# 1 of 3 Creation Date : April 03, 2017 (GMT)

### C0603X6S1C223M030BC



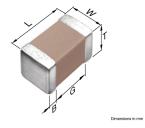






#### TDK item description C0603X6S1C223MT\*\*\*\*

Applications	Commercial Grade	
Feature	General General (Up to 50V)	
Series	C0603 [EIA 0201]	
Status	Production (Not Recommended for New Design)	



Size		
Length(L)	0.60mm ±0.03mm	
Width(W)	0.30mm ±0.03mm	
Thickness(T)	0.30mm ±0.03mm	
Terminal Width(B)	0.10mm Min.	
Terminal Spacing(G)	0.20mm Min.	
Recommended Land Pattern (PA)	0.25mm to 0.35mm	
Recommended Land Pattern (PB)	0.20mm to 0.30mm	
Recommended Land Pattern (PC)	0.25mm to 0.35mm	

Electrical Characteristics		
Capacitance	22nF ±20%	
Rated Voltage	16VDC	
Temperature Characteristic	X6S(±22%)	
Dissipation Factor (Max.)	10%	
Insulation Resistance (Min.)	4545ΜΩ	

Other		
Soldering Method	Reflow	
AEC-Q200	No	
Packing	Punched (Paper)Taping [180mm Reel]	
Package Quantity	15000pcs	

<sup>!</sup> Images are for reference only and show exemplary products. ! This PDF document was created based on the data listed on the TDK Corporation website.

<sup>!</sup> All specifications are subject to change without notice.

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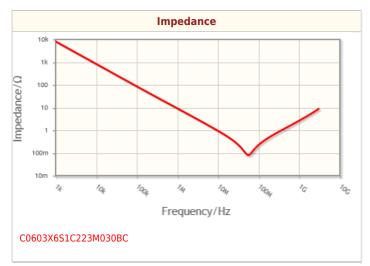


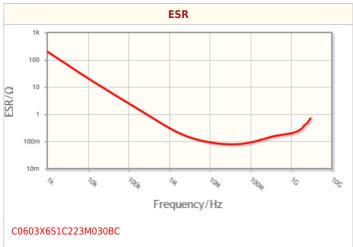


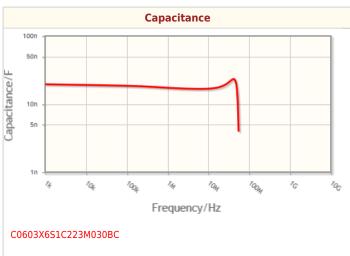


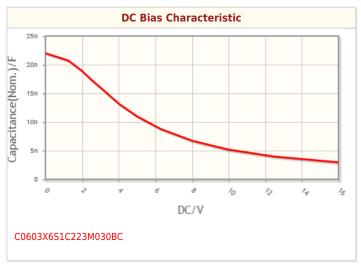


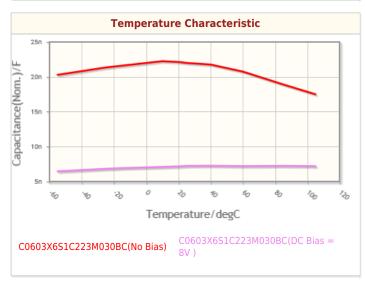
### Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

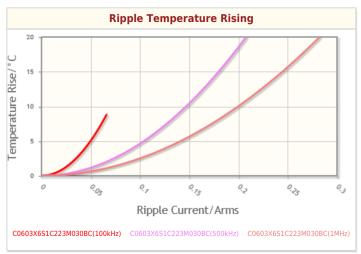












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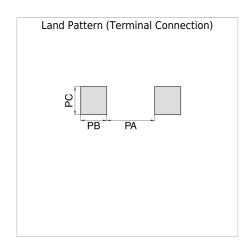






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## **Associated Images**



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